

Abstract of the Disclosure:

In the fabrication of stacked vias, metal islands referred to as landing pads are introduced for the purpose of contact-connection between the vias that are arranged one above the

5 other. The metal islands project laterally beyond the vias to a significant extent on account of the line shortening effect.

The vias arranged in layers lying one above the other are laterally offset with respect to one another. The landing pad of the invention is configured as an interconnect running

10 between the vias. On account of the line shortening effect,

which is less critical for longer tracks, contact areas

provided at the ends of the interconnect do not have to be

chosen to be as large as the square contact areas of

conventional metal islands and can therefore be accommodated

15 to save more space on a circuit layout to be miniaturized. The

shrink factor of such a semiconductor structure is increased.